

Supplementary information

Focused Electron Beam Induced Deposition of Magnetic 3D Iron Nano-bridges through Dwell Time Simulation Assistance with Plasma-Based Post Growth Purification

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Supporting Information:

1. The Growth-Control Model of Fe-3D Nanoprinting:

The model used on our experiments on Focused Electron Beam Induced Deposition (FEBID) represents a desorption-dominated process that incorporates heating effects through a resistance model and spatial distribution effects as described in the main text eq. (1)

The core of the model is a proximity function that calculates the desorption rate or probability at different locations based on two key factors: resistance and distance. It predicts how a material removal or desorption event occurs based on two primary factors: the local resistance, which affects heating, and the distance from a central point, which determines the spatial spread of the process. The function combines a base growth rate with two exponential terms.

The first term, e^{-kRT} accounts for how the process is affected by heat resistance, which likely represents a heating effect. Higher resistance leads to higher heat accumulation, increasing the deposition rate, which in turn inhibits the growth process.

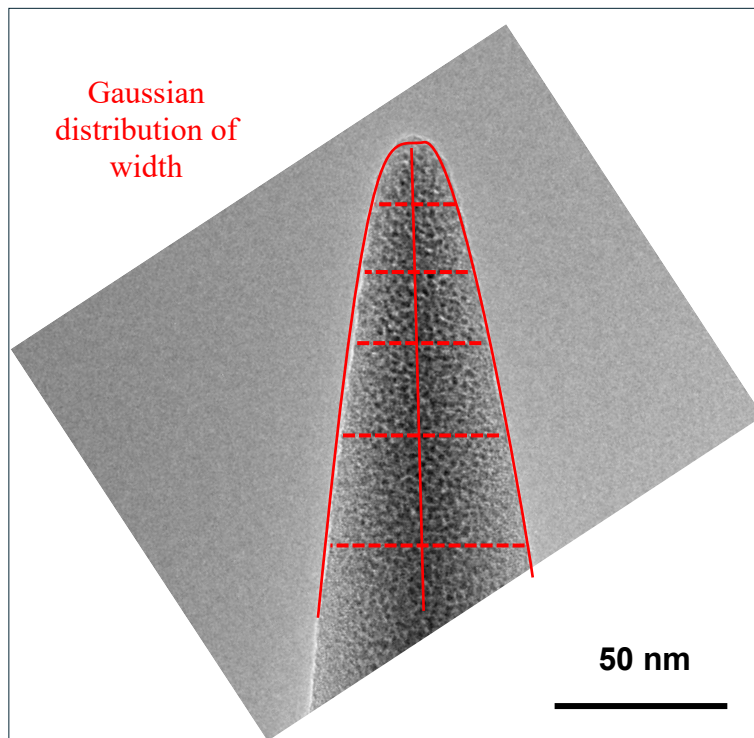
The second term, $e^{\frac{-r^2}{2\sigma^2}}$ is a Gaussian function that models how the effect gets narrow with distance from a central point. The σ parameter controls the spatial spread of this effect.

30 The behaviour of the model aligns with physical expectations, maximum growth occurs in
31 regions with low resistance and small distances, where heating is under control and the spatial
32 effect is strongest. These principles make the model applicable to nanofabrication for 3d nano
33 printing of Fe. The model consists of three key parameters that have a significant influence on
34 the growth process. The first parameter is growth rate (G_r) represents the base rate at which
35 desorption or material removal occurs, serving as the fundamental driving factor of the growth
36 process. Secondly, the temperature scaling factor (k) determines how strongly resistance
37 impacts the growth rate, with higher values of k making the process more sensitive to variations
38 in heating resistance. This means that even small changes in resistance can significantly alter
39 the desorption behavior when k is large. Lastly, the deposit width variation of sigma (σ)
40 controls the spatial distribution of the effect, dictating how quickly the desorption influence
41 diminishes with distance as shown in as shown in supplementary figure 1. A larger σ results in
42 a broader spatial spread, while a smaller σ makes the effect more localized. Together, these
43 parameters define how growth processes vary based on local resistance and distance from the
44 central point.

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49 *Supplementary figure 1. The standard deviation of the deposited width, following a Gaussian*
 50 *distribution, represents variability in the deposition process and significantly influences 3D*
 51 *nanostructure growth. A higher σ causes greater fluctuations, leading to irregularities or failures in*
 52 *the final structure. This variation can be controlled by the model parameter (σ).*

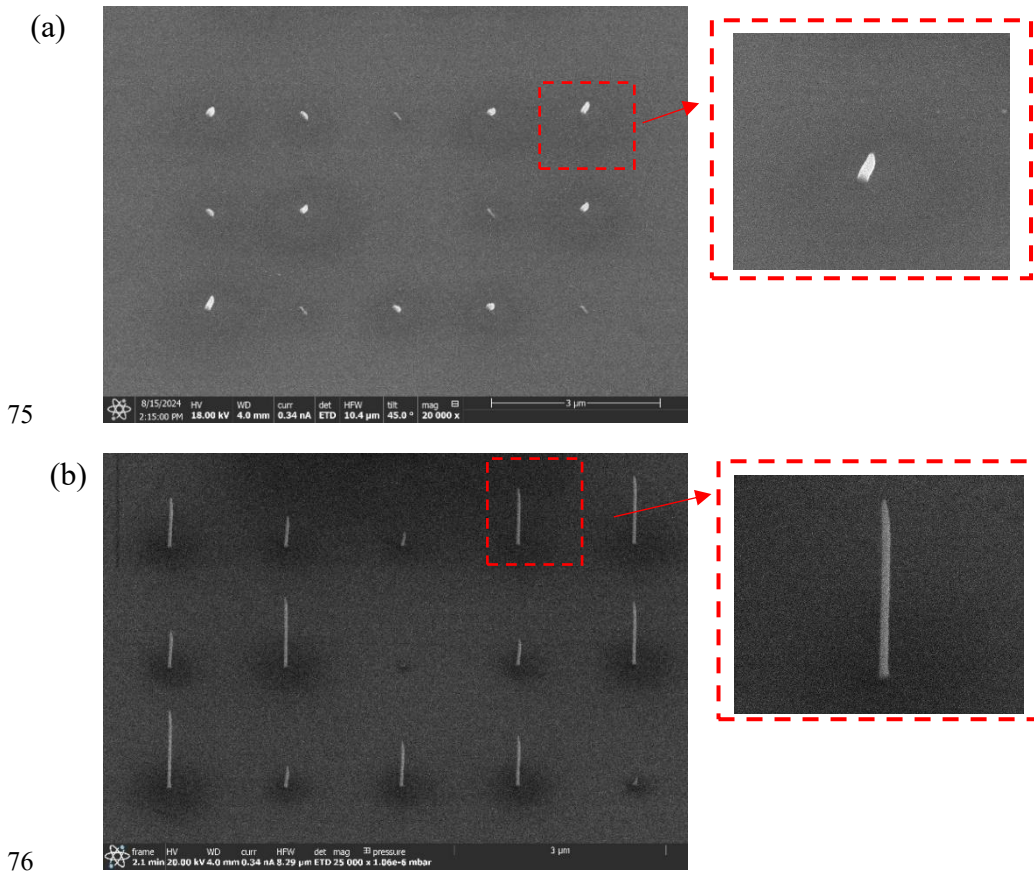
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54 **2. E-beam Voltage and current optimization:**

55 The effects of voltage (V) and current (I) on FEBID are crucial for controlling resolution,
 56 deposition rate, and thermal effects. It is important to optimize the voltage and current without
 57 any control interference from the model that explained in the pervious section^{1,2}. Voltage
 58 influences growth accuracy, with higher voltages improving lateral precision due to reduced
 59 electron interaction volume. It also affects penetration depth, altering secondary and
 60 backscattered electron distributions, which impact precursor dissociation. Additionally, higher
 61 voltages contribute to beam heating, influencing precursor coverage and desorption rates.

62 Current primarily impacts the deposition rate, as higher currents provide more electrons for
 63 precursor dissociation. However, increased current also leads to thermal effects, raising local
 64 temperatures and potentially altering deposit characteristics. Moreover, higher currents can
 65 intensify proximity effects, such as unwanted deposition around the target area due to scattered

66 electrons. The combined effects of voltage and current determine growth stability, especially
67 in 3D structures, where beam heating can cause distortions. They also influence precursor
68 dissociation pathways, affecting deposit composition, and play a role in electron scattering,
69 shaping the spatial distribution of the deposition. The calibration process, which consists of a
70 15-nanowire array, is necessary without any interference from the FEBID model due to the
71 requirement of balancing voltage and current to achieve precise control over resolution, growth
72 rate, and deposit properties while minimizing undesirable effects like excessive heating or
73 unintended deposition. The optimum deposition conditions can result in high Gr with sharp
74 straight morphological structures as shown on the supplementary figure 2.



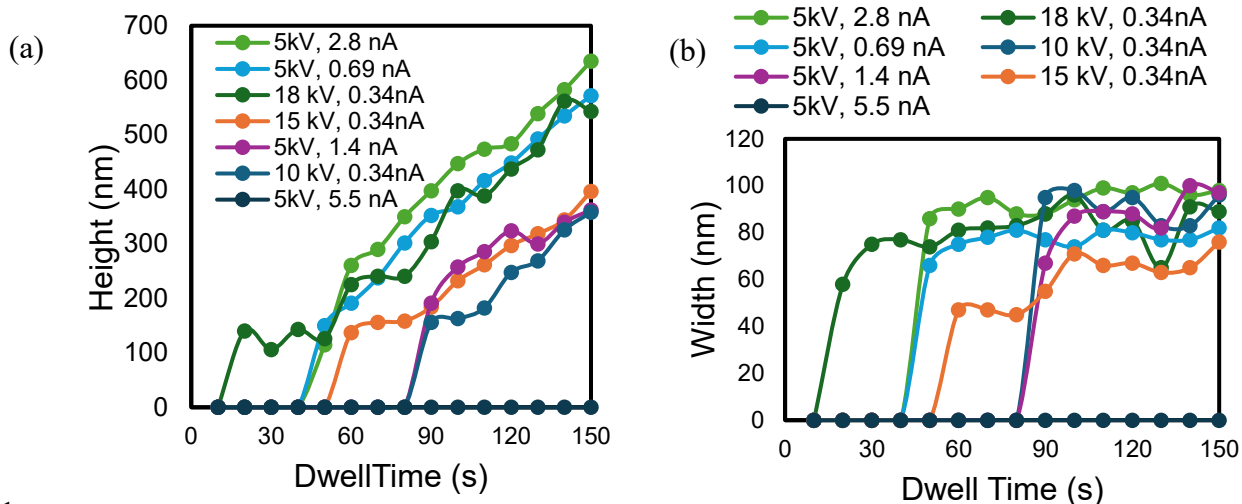
77 *Supplementary figure 2. Two set of calibration arrays of 15 NWs with the same total dwell time, (a)*
78 *representing a lower quality and lower Gr while (b) representing high quality and high Gr. The*
79 *optimum NWs for having suitable deposition conditions should be sharp with highest Gr as possible.*

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81 **3. Temperature Effects on the growth process:**

82 The effect of temperature on the precursor, $\text{Fe}_2(\text{CO})_9$ reaction FEBID is complex and
83 significantly influences the deposition process. Temperature impacts various aspects, including
84 precursor coverage, dissociation rate, deposit composition, and growth rate. Higher
85 temperatures generally decrease the residence time of $\text{Fe}_2(\text{CO})_9$ molecules on the substrate
86 surface, potentially reducing precursor coverage and growth rate if too elevated. However,
87 increased temperatures can also enhance the dissociation of $\text{Fe}_2(\text{CO})_9$, leading to more efficient
88 deposition and deposits with higher iron content and lower carbon contamination. The growth
89 rate exhibits a temperature-dependent behavior, where moderate increases can boost growth by
90 enhancing precursor mobility and dissociation, but excessive temperatures may hinder growth
91 due to rapid desorption³⁻⁵. Temperature also affects thermal desorption of precursors and
92 products, surface diffusion of adsorbed species, and can lead to thermal decomposition if too
93 high. Additionally, the electron beam itself induces localized heating, further complicating the
94 temperature effects. Optimizing temperature in this process requires careful balancing of
95 various factors to achieve the desired controlling process parameter of growth rates. The
96 optimal temperature can be varying based on specific application requirements and other
97 process parameters. The optimized temperature for $\text{Fe}(\text{CO})_5$ FEBID has been found to be 37°C,
98 while 28°C resulted in a lower Gr over a wide range of (V) and (I), as shown in supplementary
99 figure 3.

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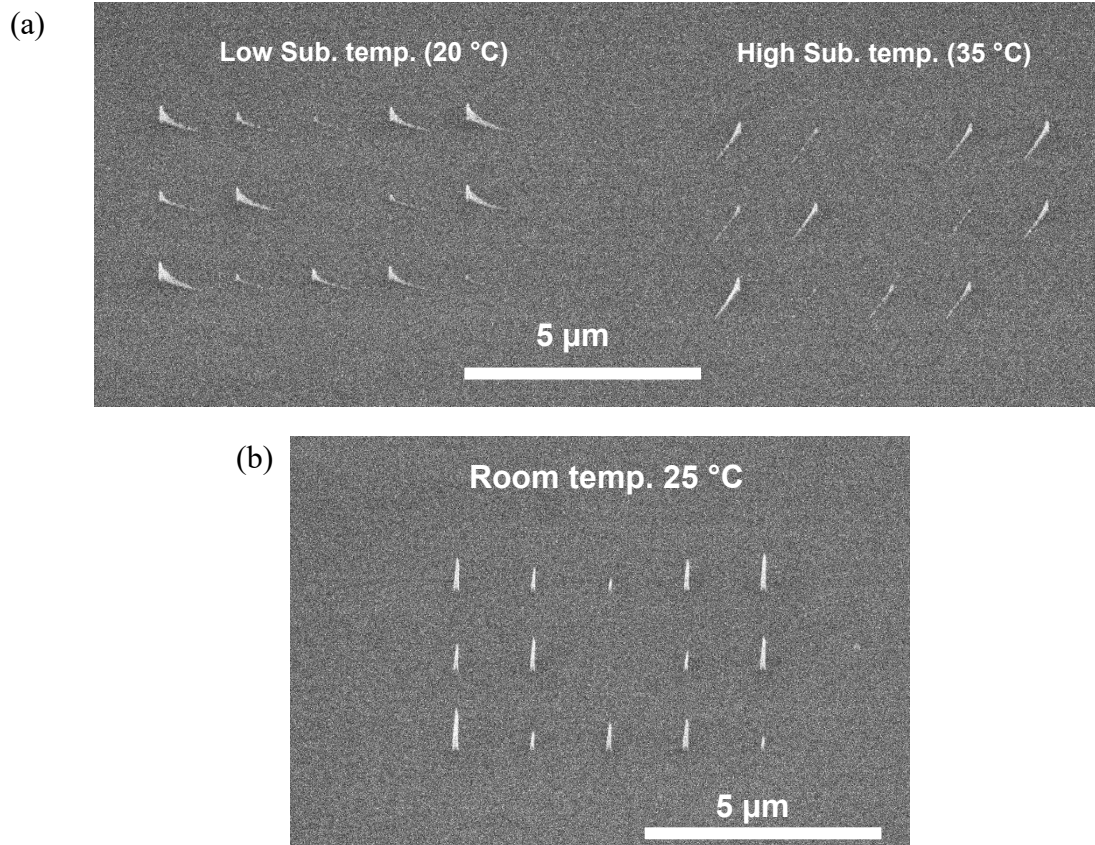
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102 *Supplementary figure 3. (a) Analytical statistical graph used to determine the vertical growth rate (Gr)*
 103 *of the nanowires, plotting deposit height versus deposition time. (b) Analytical statistical graphs*
 104 *showing width dependent time at different deposition conditions that can determine: (i) The thermal*
 105 *resistance scaling factor (K) as a function of nanowire length and width, indicating heat dissipation*
 106 *characteristics. (ii) The standard deviation of the deposit width (σ) versus deposition time, illustrating*
 107 *lateral growth precision.*

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109 The substrate temperature plays a crucial role in determining the growth behavior of the
 110 material as shown in supplementary figure 4, deviations from room temperature, whether lower
 111 or higher, lead to a drifting growth pattern. This instability in growth can be attributed to
 112 thermal effects, where fluctuations in temperature cause expansion and contraction of the
 113 substrate. These structural changes influence the material deposition process, potentially
 114 leading to defects or irregular growth. In contrast, growth at room temperature exhibits a more
 115 stable and uniform structure, suggesting that maintaining an optimal substrate temperature is
 116 essential for achieving controlled and consistent material formation.

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120 *Supplementary Figure 4. SEM images show the effect of substrate temperature on the growth process.*
 121 *(a) Lower or higher temperatures result in drifting growth compared to (b) growth at room temperature.*
 122 *The continuous drifting could be attributed to the shrinking and expansion effect of the substrate.*
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124 **4. Effect of magnification on quality of electron probe:**

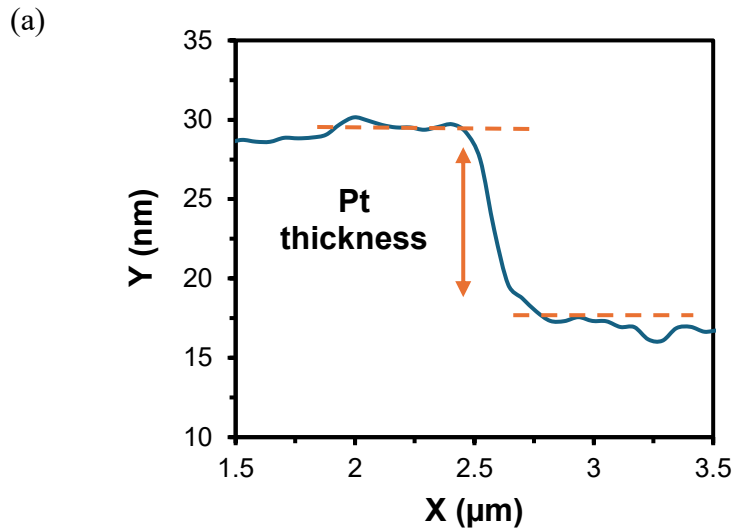
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126 The resolution of an electron microscope significantly affects the quality of imaging and
 127 FEBID, though it does not alter the electron probe itself. Instead, resolution influences how the
 128 beam scans the sample and how details are captured. Since the electron probe remains constant,
 129 achieving high-quality imaging requires precise focus and astigmatism correction. At lower
 130 resolutions, details are averaged over larger pixel areas, making the system less sensitive to
 131 small aberrations. Therefore, it is always advisable to first optimize focus and correct
 132 astigmatism at higher resolutions before switching to lower resolutions as shown in
 133 supplementary figure 5. This ensures that the electron probe is finely tuned, resulting in sharper
 134 and more accurate images. In FEBID, resolution settings affect the scanning precision, directly

135 influencing the quality of deposited structures. A well-optimized electron probe ensures precise
136 energy delivery to precursor molecules, leading to well-defined structures with improved
137 resolution and deposition control. Improper focus or astigmatism can cause blurry, irregular,
138 or less controlled deposits, especially in high-precision applications like nanostructure
139 fabrication or 3D FEBID growth of Fe. Thus, although resolution adjustments do not change
140 the electron probe itself, optimizing focus and astigmatism at high resolution is crucial for
141 achieving high-quality images and precise FEBID structures.

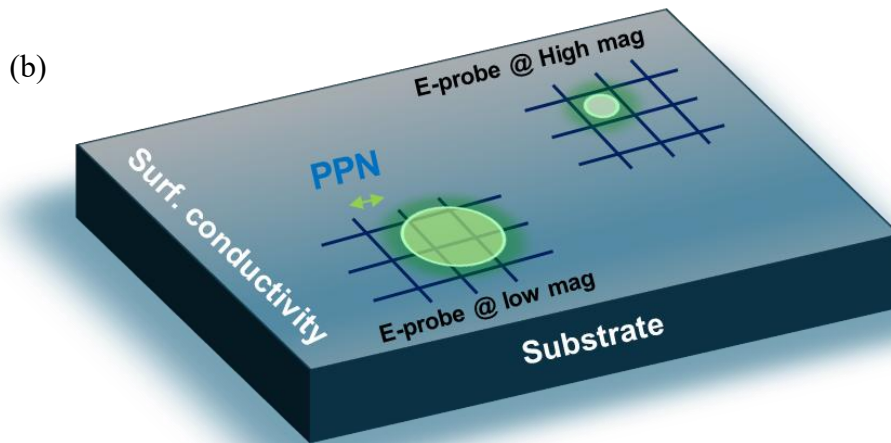
142 Coating the substrate with platinum (Pt) before performing FEBID serves several critical
143 purposes, primarily related to charge dissipation, imaging quality, and deposition control. Non-
144 conductive or poorly conductive substrates, such as Si, can accumulate charge during electron
145 beam exposure, leading to beam deflection, distortions, and unstable deposition. A thin Pt layer
146 provides a conductive path that dissipates charge, ensuring stable beam interaction and
147 preventing imaging artifacts. Additionally, Pt enhances secondary electron emission,
148 improving contrast and focus stability on scanning electron microscopy (SEM), which aids in
149 precise alignment and electron probe optimization. The uniform Pt coating also promotes
150 consistent nucleation of FEBID deposits, improving growth control and reducing variability in
151 deposit morphology. Furthermore, it protects the underlying substrate from electron-induced
152 surface modifications and contamination, preserving material integrity. In some cases, a Pt
153 layer enhances the adhesion and mechanical stability of FEBID deposits, particularly for
154 nanostructures or complex 3D geometries.

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159 *Supplementary figure 5. (a) AFM measurement of the fitted line profile Si-sub coated with pt*
 160 *representing its thickness, (b) the effect of mag on e-probe, green spot, it is always better to correct the*
 161 *focus and astigmatism at much higher resolutions to optimize the e-probe for better images and growth.*
 162

163 **5. The dwell time map simulation parameters:**

164 The second set of calibration parameters is essential for refining the layer-by-layer 3D
 165 deposition process of our used model, ensuring precise control over deposition while
 166 minimizing excessive heating. The structure parameters define the spatial configuration, where
 167 the pitch is set to 3 nm, determining the spacing between adjacent pixels or deposition points
 168 with the necessary fill requirements. The stream builder parameters regulate electron beam

169 interaction, with addressable pixels of approximately 64k, corresponding to the specific pattern
170 board resolution of the Helios PFIB 660, which defines the number of controllable pixels⁹. The
171 maximum dwell time of 5 milliseconds limits the beam dwell time to prevent overheating,
172 while the cutoff time of 0.01 milliseconds eliminates insignificant dwell times, enhancing
173 processing efficiency. The screen width of 13.8 μm defines the horizontal scanning area as a
174 function of magnification, and the scanning order, set to serpentine, enables a back-and-forth
175 scanning pattern, optimizing uniformity and efficiency. Additionally, the refresh time of 16
176 milliseconds ensures periodic updates in scanning or deposition. The calibrated single pixel
177 width is set to 50 nm, defining the resolution of scanning and deposition to maintain structural
178 precision. These parameters collectively optimize electron beam interaction, deposition
179 resolution, and thermal regulation, ensuring high-quality 3D nanostructures with controlled
180 growth and minimal structural distortions.

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182 6. Another example of 3D Fe-FEBID of a complex structure:

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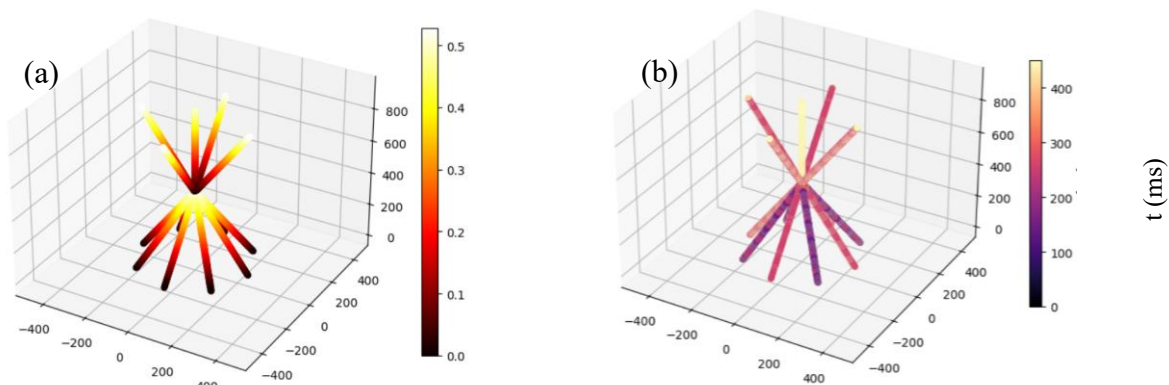
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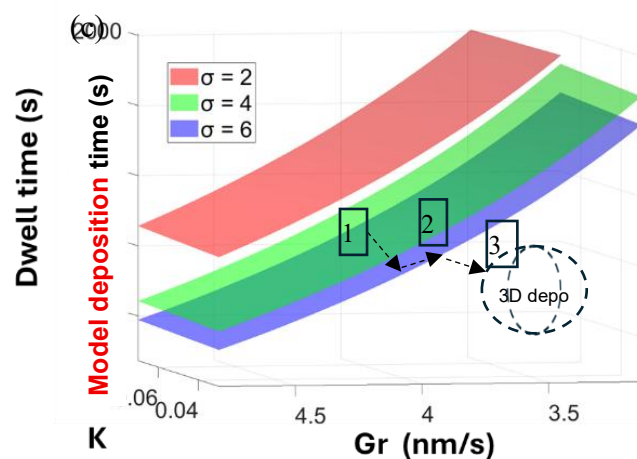
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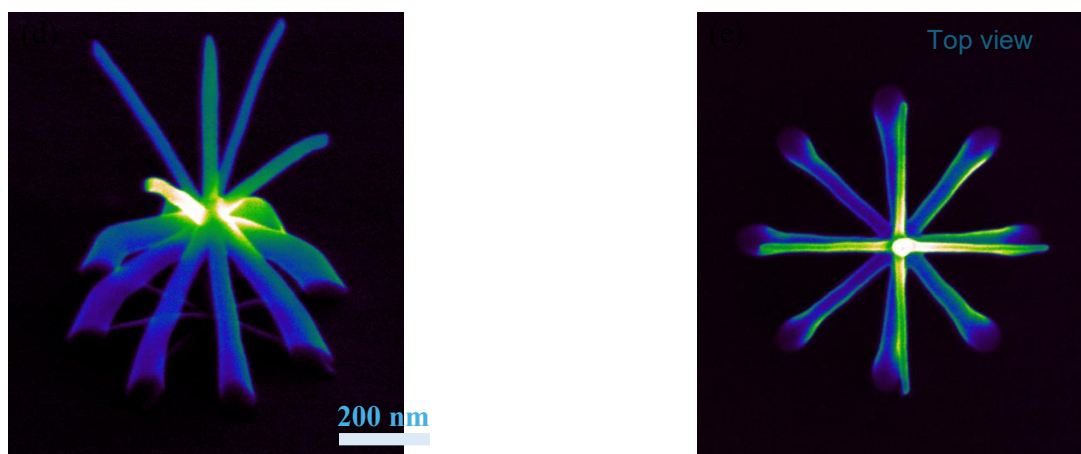
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198 *Supplementary figure 6. Demonstration of complex 3D nano printing of a flower-like nanostructure*

199 *using FEBID with optimized model parameters with extended calibration method. E-beam: 20 keV, 340*

200 *pA, precursor is Fe₂(CO)₉ preheated at 37 °C, and base pressure: 10⁻⁷ mbar. (a) Finite element*

201 *simulation of the thermal resistance distribution across the structure, with color scale indicating*

202 *heating resistance values. (b) Dwell time map generated from the stream file, showing the electron*

203 *beam exposure duration at each point of the structure. Color scale represents dwell time in*

204 *milliseconds, highlighting regions requiring longer deposition times. (c) 3D parameter space graph*

205 *illustrates the influence of Gr, K, and σ on the total dwell time for achieving successful deposition with*

206 *sharp edges as designed as indicated as 3d spot among the graphs, (d) SEM image of the deposited*

207 *structure, and (e) top view of deposited structure.*

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209 The dwell time map in Fig. 6(b), generated from the stream file, illustrates the e-beam exposure
210 duration at each point of the structure. The color scale represents dwell time in milliseconds
211 (ms), highlighting regions that require longer deposition times due to their complex geometry
212 or higher material accumulation. This 3D map provides a visual representation of the time-
213 resolved deposition process, enabling precise control over the fabrication of intricate features.
214 Figure 4(c) presents a 3D parameter space graph illustrating how the simulated total dwell time
215 is influenced by key parameters Gr , K , σ , and how this helps navigate the refinement of
216 necessary values for printing the 3D structure. The graph explains the interplay between these
217 parameters and their collective impact on the optimized dwell time required to deposit the
218 structure successfully and promptly for achieving sharp edges and consistent geometries. The
219 navigation method for the 3D graph follows the same approach explained in Figure 2(d) in
220 exactly a similar way in figure 2(d). The 3D spot indicated in the graph represents an
221 approximation of a regime set that ensures successful deposition with sharp edges, as designed.
222 This graphic navigation process is dependent on the geometry of complex nanostructures, and
223 it is essential for achieving high-fidelity. The SEM image in Fig. 6(d)-(e) showcases the final
224 flower-like nanostructure, which exhibits sharp edges and well-defined features, demonstrating
225 the effectiveness of the refined model parameters through the extended calibration method. The
226 top view further emphasizes the intricate details and uniformity achieved during deposition. It
227 is noted that the thicker bottom could be caused by mechanical stress or carbon further building
228 up during the growth. The results highlight the successful fabrication of a complex 3D
229 nanostructure, supported by simulations and parameter optimization, demonstrating the
230 potential of FEBID for Fe 3D nano printing fabrication. Each bath in Figure 6(c) has been
231 characterized individually in comparison to the model shown in Figure 6(a) (b).

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